KAMAYA OHM

Spec. No.: HFC-K-HTS-0001 /3

Date: 2017. 1. 10

Specification

Title: CHIP FUSE; RECTANGULAR TYPE

Style: HFC32[Optional code:AG]

RoHS COMPLIANCE ITEM
Halogen and Antimony Free

Product specification contained in this specification are subject to change at any time without notice If you have any questions or a Purchasing Specification for any quality Agreement is necessary, please contact our sales staff.



Hokkaido Research Center Approval by: T. Sannomiya Drawing by: M. Shibuya

Note: Stock conditions

Temperature: $+5^{\circ}$ C ~ $+35^{\circ}$ C Relative humidity: 25% ~ 75%

The period of guarantee: Within 2 year from shipmen t by the company.

Solderability shall be satisfied.

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1. Scope

1.1 This specification covers the detail requirements for chip fuses; rectangular type, style of HFC32 [Optional code: AG].

1.2 Applicable documents

UL248-1-2000 Low-Voltage Fuses-Part1: General Requirements

UL248-14-2000 Low-Voltage Fuses-Part14: Supplemental Fuses

CSA C22.2 No.248.1–2000 Low-Voltage Fuses-Part1: General Requirements

CSA C22.2 No.248.14-2000 Low-Voltage Fuses-Part14: Supplemental Fuses

2. Classification

Type designation shall be the following form.

2 Size

3 Rated current

802 802--> 8.0 A

4 Optional code

Symbol	Optional code
AG	Standard

5 Packaging form

99	
В	Bulk (loose package)
TP	Paper taping

3. Safety standard approval

- UL248-1 and UL248-14
- CSA C22.2, No. 248.1-00 and CSA C22.2, No. 248.14-00

The file number to be designated by UL and C-UL shall be as follows: E176847

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4. Rating

4.1 The ratings shall be in accordance with Table-1.

Table-1

	Rated current		Internal	Rated	Breaking	Time / d	Time / current characteristic		
Style	Symbol	(A)	Marking symbol	resistance value (mΩ Max.)	voltage (Vdc)	capacity (A)	Current	Pre-arcing time	
	102	1.0	102	180		76 50	200%	60s max	
	132	1.25	132	140					
	162	1.6	162	100					
	202	2.0	202	60	76				
	252	2.5	252	38					
	302	3.0	302	32					
HFC32	322	3.15	322	30					
111 002	402	4.0	402	20					
	502	5.0	502	16					
	632	6.3	632	12					
	702	7.0	702	11					
	802	8.0	802	9					
	103	10.0	103	7					
	133	12.5	133	6					

Style	Working temperature range(°C)
HFC32	-55 to +125

5. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

Symbol	Packaging form		Standard packaging quantity / units
В	Bulk (loose package)		1,000 pcs.
TP	Paper taping 8mm width, 4mm pitches		5,000 pcs.

6. Dimensions

6.1 The resistor shall be of the design and physical dimensions in accordance with Figure-1 and Table-3.

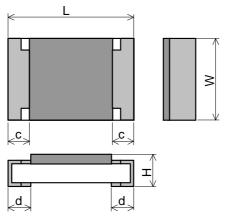


Figure-1

		lat	ole-3		Unit: mm
Style	L	W	Н	С	d
HFC32	3.2±0.2	1.6±0.15	0.6±0.1	0.5±0.25	0.5±0.25



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6.2 Net weight (Reference)

Style	Net weight(mg)
HFC32	9

7. Marking

The Marking symbol of Sub-clause 4.1 shall be marked on over coat side.

(Example) "802" → Content: HFC32 802 AG

8. Performance

8.1 Unless otherwise specified, the standard range of atmospheric conditions for tests is as follows;

Ambient temperature: 5 °C to 35 °C, Relative humidity: 45 % to 85 %, Air presser: 86 kPa to 106 kPa

If there is any doubt the results, measurements shall be made within the following:

Ambient temperature: 20 °C \pm 2 °C, Relative humidity: 60 % to 70 %, Air presser: 86 kPa to 106 kPa

8.2 The performance shall be satisfied in Table-4.

Table-4(1)

No.	Test items	Condition of test	Perform	mance requirements
1	Temperature rise	The fuse shall be mounted on the test substrate as	75 °C max	
'	Tomporataro noo	shown in Figure–2.	75 Omaz	Λ.
		Measurement temp.: 10 °C to 30 °C		
		Test current: Rated current		
		The temperature at the hottest point on the surface of the		
		fuse shall be measured after temperature equilibrium has		
		been attained.		
2	Time / current characteristic	The fuse shall be mounted on the test substrate as	Current	Pre-arcing time
		shown in Figure–2.	200%	60s max
		Test current shall be applied for continuously.		
3	Terminal bond strength of	<u>JIS C 60068-2-21 Ue1</u>	_	f internal resistance:
	the face plating	The fuse shall be mounted on the test substrate as	±10%	
		shown in Figure–2.		ence of mechanical
		Bending value: 3 mm(Among the fulcrums: 90 mm)	damage.	
		Duration: 10 s ± 1 s		
4	Resistance to soldering	Test by a piece.		f internal resistance:
	heat	Temp. of solder bath: 260 °C ± 5 °C	±10%	,
		Immersion time: 10 s ± 1 s	No evide	ence of appearance
		After immersion into solder, leaving the room temp. for 1h	damage	
		or more, and then measure the internal resistance.		
		Reflow soldering		
		Pre–heating: 150 °C ~ 180 °C, 120 s max.		
		Peak: 260 °C ± 5 °C, 10 s max.		
		Reflow cycle: 2 times		
		After immersion into solder, leaving the room temp. for 1h		
		or more, and then measure the internal resistance.		
5	Solderability	<u>JIS C 60068-2-58</u>		ce of terminal immersed
		Test by a piece		in. of 95 % covered with
		Flux: Rosin-Methanol	a new coa	ting of solder.
		Temp. of solder: bath: 235 °C ± 5 °C		
		Immersion time: 2 s ± 0.5 s		

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Table-4(2)

No.	Test items	Condition of test	Performance requirements	
6	Rapid change temperature	<u>JIS C 60068-2-14 Na</u> The fuse shall be mounted on the test substrate as shown in Figure–2. Lower temperature: –55 °C Upper temperature: +125 °C Duration of exposure at each temperature: 30 min.	Change of internal resistance:	
		Number of cycles: 5 cycles		

9. Test substrate

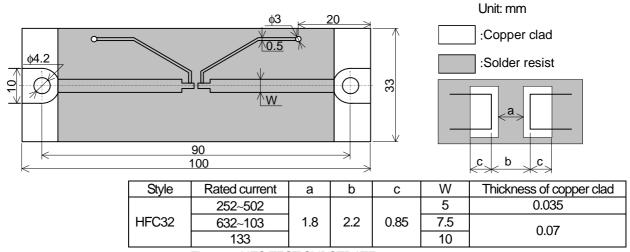


Figure-2 HFC TEST SUBSTRATE

Remark 1). Material: Epoxide woven glass

Thickness: 1.6mm

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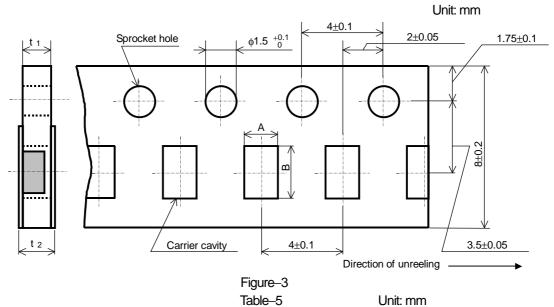
10. Taping

10.1 Applicable documents JIS C 0806-3:2014, EIAJ ET-7200C: 2010

10.2 Taping dimensions

Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-3 and Table-5.



The cover tapes shall not cover the sprocket holes.

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- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following Figure-4.

 3.6 ± 0.2

 0.8 ± 0.1

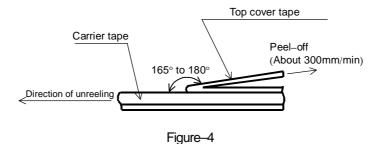
1.0max

- 6). When the tape is bent with the minimum radius for 25 mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.

 The maximum number of missing components shall be one or 0.1%, whichever is greater.

2.0±0.15

8). The fuses shall be faced to upward at the over coating side in the carrier cavity.



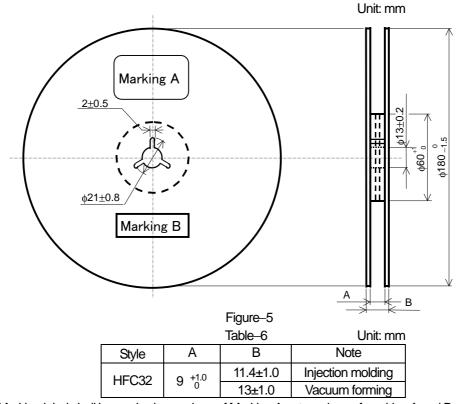
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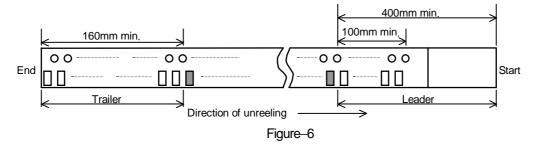
10.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure–5 and Table–6. Plastic reel (Based on EIAJ ET–7200C)



Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

10.4 Leader and trailer tape.



11. Marking on package

The label of a minimum package shall be legibly marked with follows.

11.1 Marking A

- (1) Classification (Style, Rated current, Optional code, Packaging form) (2) Quantity (3) Lot number
- (4) Manufacturer's name or trade mark (5) UL and /or C–UL recognized component mark (6) Others 11.2 Marking B (KAMAYA Control label)



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12. Recommended Derating for Rated Current

This fuse will recommend use by the current reduction value according to the following derating curve.

- Nominal Derating
 - Nominal Derating ≤ 75% of Rated Current
- Temperature Derating

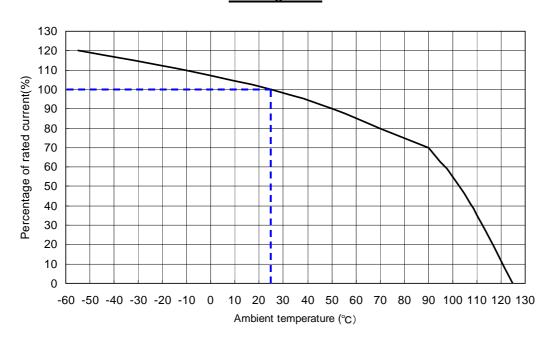
Please refer to the following graph regarding the current derating value for ambient temperature.

Ex.) If HFC32 801 (Rated Current 8.0A) is used under ambient temperature 70°C,

Kamaya recommends, less than the current value derated as below,

Rated Current: $8.0A \times (Nominal Derating: 75\% \times Temperature Derating: 80\%) = 4.8A$

Derating curve



单击下面可查看定价,库存,交付和生命周期等信息

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